L Number	Hits	Search Text	DB	Time stamp
1	424	"front opening unified pod"	USPAT; US-PGPUB; EPO; JPO;	2004/10/28 09:35
2	0	"front open unified pod" and "front opening interface mechanical standards"	DERWENT USPAT; US-PGPUB; EPO; JPO;	2004/10/28
3	1	"front open unified pod" and FIMS	DERWENT USPAT; US-PGPUB; EPO; JPO;	2004/10/28 09:31
4	70	"front open unified pod"	DERWENT USPAT; US-PGPUB; EPO; JPO;	2004/10/28 09:32
5	6	"front open unified pod" and JIG	DERWENT USPAT; US-PGPUB; EPO; JPO;	2004/10/28
6	0	"front open unified pod" and JIG and purg\$4	DERWENT USPAT; US-PGPUB; EPO; JPO;	2004/10/28 09:34
7	0	"front open unified pod" and JIG and gas	DERWENT USPAT; US-PGPUB; EPO; JPO;	2004/10/28 09:34
8	66	"front opening unified pod" and purg\$4	DERWENT USPAT; US-PGPUB; EPO; JPO;	2004/10/28 09:35
9	59	"front opening unified pod" and purg\$4 and gas	DERWENT USPAT; US-PGPUB; EPO; JPO;	2004/10/28 09:37
10	12	"front opening unified pod" and purg\$4 and gas and gap	DERWENT USPAT; US-PGPUB; EPO; JPO;	2004/10/28 09:37
_	18890	(wafer or semiconductor or substrate) and JIG	DERWENT USPAT; US-PGPUB; EPO; JPO;	2004/10/26 10:36
_	264	(wafer or semiconductor or substrate) and JIG and purg\$4	DERWENT USPAT; US-PGPUB; EPO; JPO;	2004/10/26 10:36
-	199	(wafer or semiconductor or substrate) and JIG and purg\$4 and gas	DERWENT USPAT; US-PGPUB; EPO; JPO;	2004/10/26 10:36
_	125	(wafer or semiconductor or substrate) and JIG and purg\$4 and gas and atmosphere	DERWENT USPAT; US-PGPUB; EPO; JPO;	2004/10/26 10:36
-	19	(wafer or semiconductor or substrate) and JIG and purg\$4 and gas and atmosphere and open\$4 and clos\$4 and door	DERWENT USPAT; US-PGPUB; EPO; JPO;	2004/10/26 10:44
-	1	(wafer or semiconductor or substrate) and JIG and purg\$4 and gas and atmosphere and open\$4 and clos\$4 and door and FIMS	DERWENT USPAT; US-PGPUB; EPO; JPO;	2004/10/26 10:55
-	151	(wafer or semiconductor or substrate) and FIMS	DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/26 10:55

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S	-	5	(wafer or semiconductor or substrate) and	·	2004/10/26
S			FIMS and JIG	US-PGPUB;	10:55
Second Color   Semiconductor or substrate   and clos%				EPO; JPO;	
FIMS and JIG and door and open\$4 and closs\$4   Closs\$4				DERWENT	
Clos94   (wafer or semiconductor or substrate) and FINS and JIG and door and open94 and clos94 and purg\$4 and gas   2	_	5	(wafer or semiconductor or substrate) and	USPAT;	2004/10/26
Clos94	ļ		FIMS and JIG and door and open\$4 and	US-PGPUB;	10:56
	i		clos\$4	EPO; JPO;	
FIMS and JIG and door and open\$4 and clos\$4 and purg\$4 and gas   US-PGPUB; EPO; JPO; DERWENT   USPAT; US-PGPUB; EPO; JPO; DERWENT   USPAT; U	ļ			DERWENT	
FIMS and JIG and door and open\$4 and clos\$4 and purg\$4 and gas   US-PGPUB; EPO; JPO; DERWENT   USPAT; US-PGPUB; EPO; JPO; DERWENT   USPAT; U	_	1	(wafer or semiconductor or substrate) and	USPAT;	2004/10/26
clos\$4 and purg\$4 and gas				US-PGPUB;	10:56
2				EPO; JPO;	
FIMS and JIG and door and open\$4 and clos\$4 and gas   12:46   12:46   12:46   13:00					
FIMS and JIG and door and open\$4 and clos\$4 and gas   12:46   12:46   12:46   13:00	_	2	(wafer or semiconductor or substrate) and	USPAT;	2004/10/26
Clos\$4 and gas					
DERWENT   US-PGPUB;   EPO; JPO; DERWENT   US-PGPUB;   EPO; J	!			EPO; JPO;	
2 (purg\$3 adj gas) with door and JIG USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; USPAT; USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; USPAT; USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT;	İ		,		
1	_	2	(purg\$3 adi gas) with door and JIG		2004/10/26
- 1 (purg\$3 adj gas) with door and FIMS		_	, , , , , , , , , , , , , , , , , , , ,	· ·	
-				•	
1					
- 71 (purg\$3 adj gas) with door	_	1	(purg\$3 adi gas) with door and FIMS		2004/10/26
- 71 (purg\$3 adj gas) with door USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EP		_	'Earling and lane'	· · · · · · ·	, ,
- 71 (purg\$3 adj gas) with door  - 49 (purg\$3 adj gas) with door and (substrate or semiconductor or wafer)  - 49 (purg\$3 adj gas) with door and (substrate or semiconductor or wafer)  - 41 (purg\$3 adj gas) with door and (substrate or semiconductor or wafer) and open\$4 and clos\$4  - 41 (purg\$3 adj gas) with door and (substrate or semiconductor or wafer) and open\$4 and clos\$4 and gap  - 14 (purg\$3 adj gas) with door and (substrate or semiconductor or wafer) and open\$4 and clos\$4 and gap  - 1844 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate)  - 1047 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4  - 1047 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4  - 1047 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4  - 1047 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4  - 1047 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4  - 1047 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig and fims  - 21 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig EPO; JPO; DERWENT USPAT; 2004/10/26 US-PGPUB; 2004/10/26 US-PGPUB; 2004/10/26 US-PGPUB; 2004/10/26 US-PGPUB; 2004/10/26 US-PGPUB; 2004/10/26 US-					·
- 71 (purg\$3 adj gas) with door  - 49 (purg\$3 adj gas) with door and (substrate or semiconductor or wafer) - 41 (purg\$3 adj gas) with door and (substrate or semiconductor or wafer) and open\$4 and clos\$4 - 41 (purg\$3 adj gas) with door and (substrate or semiconductor or wafer) and open\$4 and clos\$4 - 44 (purg\$3 adj gas) with door and (substrate or semiconductor or wafer) and open\$4 and clos\$4 and gap - 44 (purg\$3 adj gas) with door and (substrate or semiconductor or wafer) and open\$4 and clos\$4 and gap - 45 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) - 46 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 (purg\$5 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 (purg\$6 with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 (purg\$6 with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 (purg\$6 with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 (purg\$6 with gap or door) and (purg\$6 with gap or door		1			
September   13:05   13:05   13:05   13:05   13:05   13:05   13:05   13:05   13:05   13:05   13:06	_	71	(nurg\$3 adi gas) with door		2004/10/26
- 49 (purg\$3 adj gas) with door and (substrate or semiconductor or wafer)  - 41 (purg\$3 adj gas) with door and (substrate or semiconductor or wafer) and open\$4 and clos\$4  - 14 (purg\$3 adj gas) with door and (substrate or semiconductor or wafer) and open\$4 and clos\$4  - 14 (purg\$3 adj gas) with door and (substrate or semiconductor or wafer) and open\$4 and clos\$4 and gap  - 1844 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate)  - 1047 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate)  - 777 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4  - 10 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4  - 10 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4  - 11 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4  - 12 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig and fims (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig and fims (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig and fims (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig and fims (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig and fims (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) (purg\$3 with gas) and (gas with (gap or door)) garwent (purg\$4 and clos\$4 and jig and fims (purg\$4 and clos\$4 and jig and fims (purg\$4 and clos\$4 and jig and fims (purg\$4 and clos\$4 and	-	'1	(purgys ad) gas/ wrom door		
- 49 (purg\$3 adj gas) with door and (substrate or semiconductor or wafer)  - 41 (purg\$3 adj gas) with door and (substrate or semiconductor or wafer) and open\$4 and clos\$4  - 14 (purg\$3 adj gas) with door and (substrate or semiconductor or wafer) and open\$4 and clos\$4 (purg\$3 adj gas) with door and (substrate or semiconductor or wafer) and open\$4 and clos\$4 and gap  - 1844 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate)  - 1047 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate)  - 777 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4  - 1 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4  - 1 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4  - 1 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4  - 1 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig and fims  - 2 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig and fims  - 2 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig and fims  - 2 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig and fims  - 2 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig and fims  - 2 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig and fims  - 2 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig and fims			,	· · · · · · · · · · · · · · · · · · ·	13.03
- 49 (purg\$3 adj gas) with door and (substrate or semiconductor or wafer)  - 41 (purg\$3 adj gas) with door and (substrate or semiconductor or wafer) and open\$4 and clos\$4  - 14 (purg\$3 adj gas) with door and (substrate or semiconductor or wafer) and open\$4 and clos\$4  - 14 (purg\$3 adj gas) with door and (substrate or semiconductor or wafer) and open\$4 and clos\$4 and gap  - 1844 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate)  - 1047 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4  - 1047 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4  - 1047 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4  - 1047 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4  - 1047 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4  - 1048 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4  - 1049 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4  - 1040 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4  - 1040 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig and fims (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig and (gas with (gap or door)) and (wafer or semiconductor or substr			,		
Or semiconductor or wafer   US-PGPUB;   EPO; JPO; DERWENT   USPAT;   USPA		10	/nurge2 add gag/ with door and /guhetrate	· ·	2004/10/26
- 41 (purg\$3 adj gas) with door and (substrate or semiconductor or wafer) and open\$4 and clos\$4  - 14 (purg\$3 adj gas) with door and (substrate or semiconductor or wafer) and open\$4 and clos\$4 and gap  - 1844 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or semiconductor or substrate)  - 1047 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate)  - 777 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4  - 1 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4  - 1 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4  - 2 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4  - 2 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig and fims  - 2 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig and fims  - 2 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig and fims  - 2 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig part of the property	-	49		· ·	
- 41 (purg\$3 adj gas) with door and (substrate or semiconductor or wafer) and open\$4 and clos\$4  - 14 (purg\$3 adj gas) with door and (substrate or semiconductor or wafer) and open\$4 and clos\$4 and gap  - 1844 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or semiconductor or substrate)  - 1047 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate)  - 1047 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate)  - 1047 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate)  - 1 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4  - 1 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4  - 1 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig and fims  - 21 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig and fims  - 21 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig and fims  - 21 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig gep0; JPO; DERWENT  - 21 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig gep0; JPO; DERWENT  - 21 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig gep0; JPO; DERWENT  - 21 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) gep0; JPO; DERWENT  - 21 (purg\$3 with gas) and (gas with (gap or door)) gep0; JPO; DERWENT  - 22004/10/26  - 23 (13:42  - 2004/10/26  - 2004/10/26  - 2004/10/26  - 2004/10/26  - 2004/10/26  - 2004/10/26  - 2004/10/26  - 2004/10/26			or semiconductor or water,	· ·	13.00
- 41 (purg\$3 adj gas) with door and (substrate or semiconductor or wafer) and open\$4 and clos\$4  - 14 (purg\$3 adj gas) with door and (substrate or semiconductor or wafer) and open\$4 and clos\$4  - 14 (purg\$3 adj gas) with door and (substrate or semiconductor or wafer) and open\$4 and clos\$4 and gap  - 1844 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate)  - 1047 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate)  - 777 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4  - 1 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4  - 1 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig and fims  - 21 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig and fims  (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig and fims  (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig and fims  (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig and fims  (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig and fims  (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig and fims  (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig and fims  (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig and fims					
or semiconductor or wafer) and open\$4 and clos\$4  - 14 (purg\$3 adj gas) with door and (substrate or semiconductor or wafer) and open\$4 and clos\$4 and gap  - 1844 (purg\$3 with gas) and (gas with (gap or door))  - 1047 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate)  - 777 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate)  - 1047 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate)  - 1048 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4  - 1049 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4  - 1040 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig and fims  - 15 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig and fims  - 16 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig and fims  - 17 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig and fims  - 1840 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig and fims  - 19 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig and fims  - 19 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig and fims  - 19 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig and fims	1	41	/munge2 add goal with door and /gubstrate		2004/10/26
clos\$4  clos\$4  (purg\$3 adj gas) with door and (substrate or semiconductor or wafer) and open\$4 and clos\$4 and gap  1844  (purg\$3 with gas) and (gas with (gap or door))  (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate)  1047  (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate)  1047  (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate)  1047  (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4  1047  1047  (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4  1047  1047  (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4  105-PGPUB; 13:44  1047  1047  1047  1047  105-PGPUB; 13:44  105-PGPUB; 13:45  105-PGPUB; 13:45  105-PGPUB;	-	41		· ·	
- 14 (purg\$3 adj gas) with door and (substrate or semiconductor or wafer) and open\$4 and clos\$4 and gap  - 1844 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate)  - 1047 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4  - 1047 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4  - 1 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4  - 1 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4  - 1 (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig and fims (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig and fims (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig and fims (purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig EPO; JPO; DERWENT (USPAT; USPAT; USPAT				· ·	13.00
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